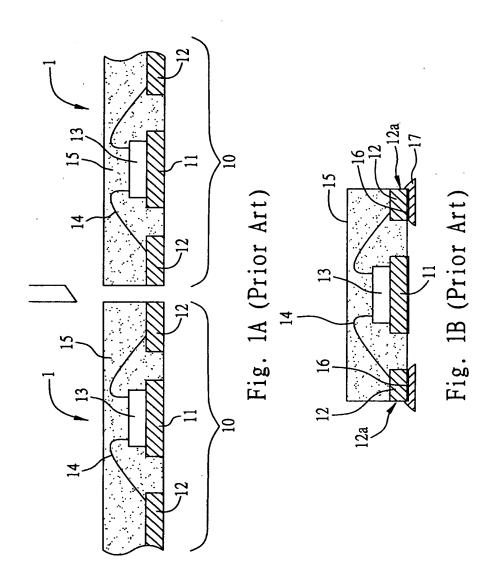
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SAME

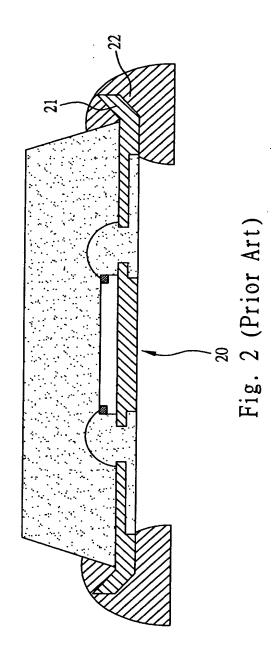
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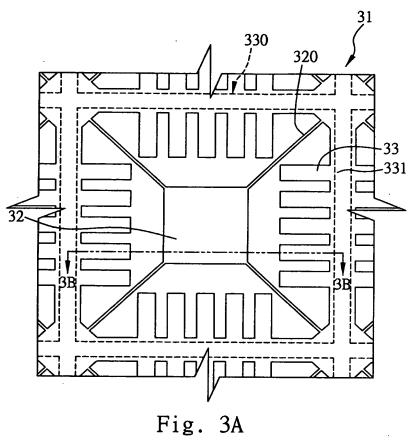
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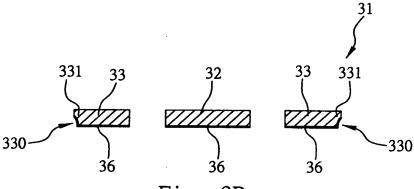


Fig. 3B

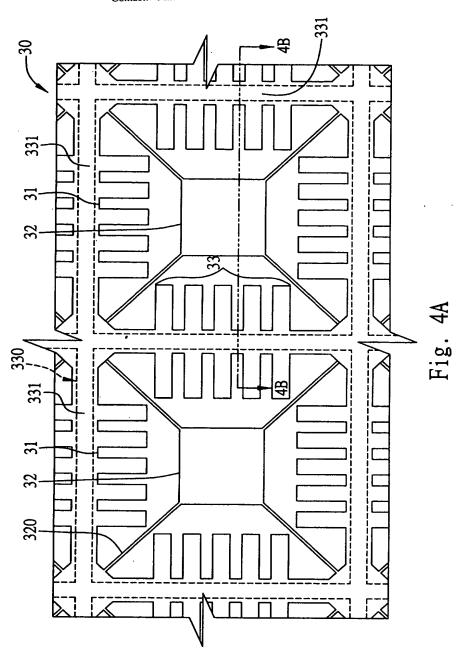
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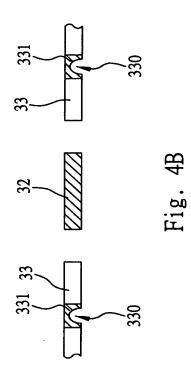


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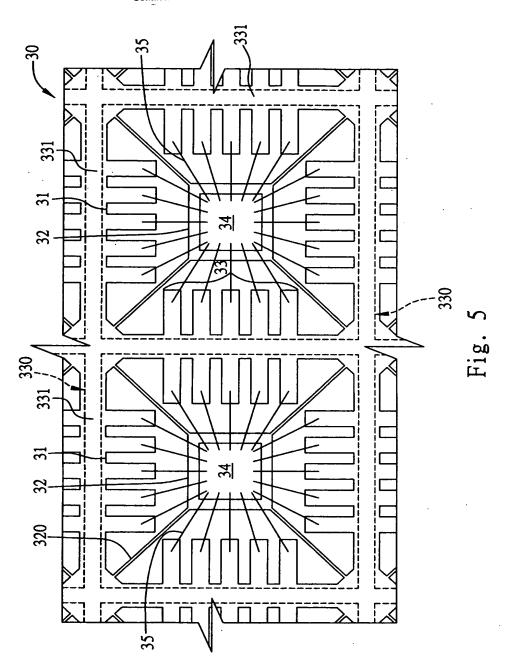
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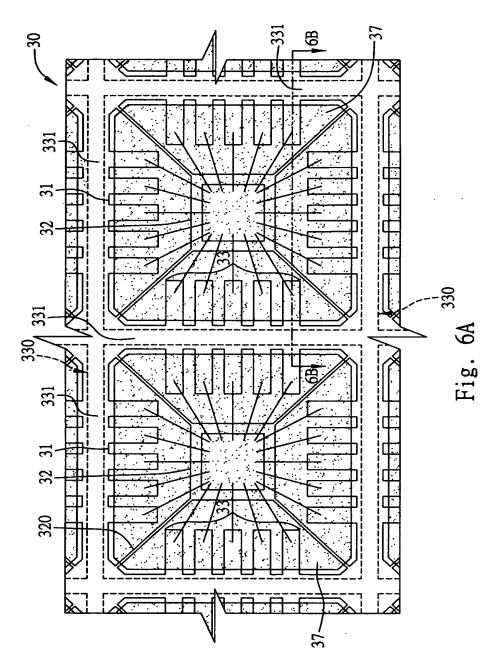
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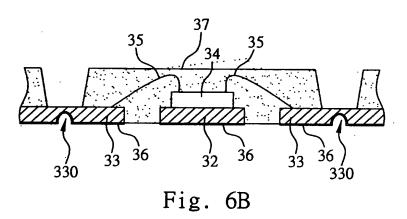
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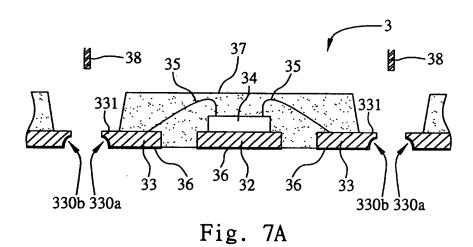
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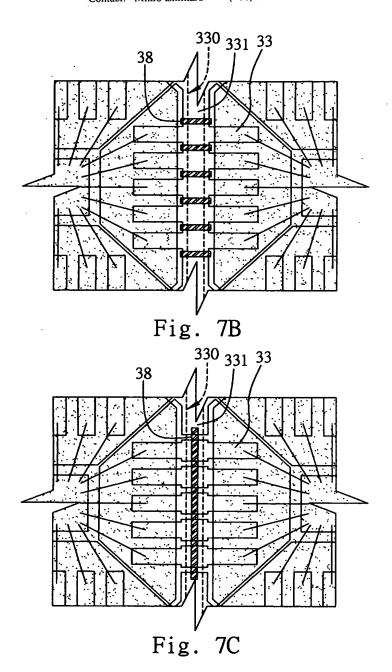


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